

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Wen-Ching Chen	:	Group
Serial No:	10/662,433	:	Art Unit # 2878
Filed:	16 September 2003	:	Examiner:
Title:	CHIP SCALE PACKAGE STRUCTURE FOR AN IMAGE	:	D.J. Williams

**AMENDMENT AFTER FINAL OFFICE ACTION**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Responsive to the Office Action dated 31 July 2006, please amend the above-referenced Patent Application as follows:

**Amendments to the Claims** are reflected in the Listing of Claims which begins on page 2 of this paper.

**Remarks** begin on page 7 of this paper.